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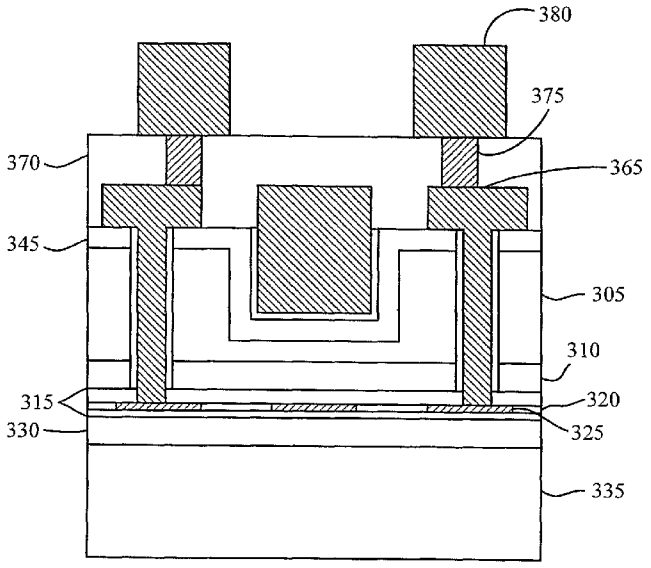
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(54) Title: STACKABLE WAFER OR DIE PACKAGING WITH ENHANCED THERMAL AND DEVICE PERFORMANCE



(57) Abstract: A substrate has a device layer (210, 310) and metallization region (230, 315) Within the substrate are provided electrically conductive through vias (270, 350) and thermally conductive regions (260, 365). The thermally conductive regions may be formed by deposition into a trench, or by patterning. The substrate may be provided in a stacked arrangement.

WO 2007/050754 A3

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